



### 30V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	Rds(on) max	I <sub>D MAX</sub> T <sub>A</sub> = +25°C
30V	$35m\Omega$ @ $V_{GS} = 10V$	5.5A
30 V	$45m\Omega @ V_{GS} = 4.5V$	4.9A

## **Description**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## **Applications**

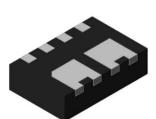
- DC Motor Control
- DC-AC Inverters

# **Features**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

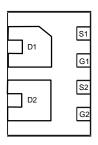
### **Mechanical Data**

- Case: V-DFN3020-8
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.011 grams (Approximate)

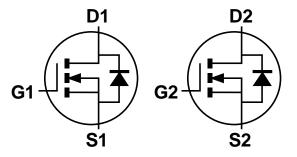


V-DFN3020-8





Bottom View Pin Configuration



Q1 N-Channel MOSFET

Q2 N-Channel MOSFET

**Equivalent Circuit** 

## **Ordering Information** (Note 4)

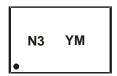
Part Number	Case	Packaging
DMN3035LWN-7	V-DFN3020-8	3,000/Tape & Reel
DMN3035LWN-13	V-DFN3020-8	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/quality/lead\_free.html.

## **Marking Information**

V-DFN3020-8



N3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2011	2012	2013	2014	2015	2016	2017
Code	Υ	Z	Α	В	С	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		$V_{DSS}$	30	V	
Gate-Source Voltage		$V_{GSS}$	±20	V	
Continuous Drain Current (Note 6) $V_{GS} = 10V$ Steady $T_{A} = +25^{\circ}C$ State $T_{A} = +70^{\circ}C$			I <sub>D</sub>	5.5 4.4	Α
Maximum Continuous Body Diode Forward Curre	ent (Note 6)	I <sub>S</sub>	1	Α	
Pulsed Drain Current		I <sub>DM</sub>	30	Α	
Avalanche Current (Note 7) L = 0.1mH		I <sub>AS</sub>	13	Α	
Avalanche Energy (Note 7) L = 0.1mH			E <sub>AS</sub>	9.0	mJ

## **Thermal Characteristics**

Characteristic		Symbol	Value	Units
Total Dawar Dissination (Note 5)	T <sub>A</sub> = 25°C	Б	0.77	w
Total Power Dissipation (Note 5)	$T_A = 70$ °C	P <sub>D</sub>	0.49	VV
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Б	162	°C/W
mermai Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	116	C/VV
Total Dawer Dissipation (Note 6)	$T_A = 25^{\circ}C$	6	1.78	w
Total Power Dissipation (Note 6)	T <sub>A</sub> = 70°C	P <sub>D</sub>	1.10	VV
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	71	°C/W
mermai Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	50	C/VV
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	10.7	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to 150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>		_	1.0	μΑ	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0		2.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D		26	35	mΩ	$V_{GS} = 10V, I_D = 4.8A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		34	45	11152	$V_{GS} = 4.5V, I_D = 4.3A$	
Diode Forward Voltage	$V_{SD}$		0.75	1.1	٧	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	399	_	pF	151/11/ 01/	
Output Capacitance	Coss		57	_	pF	$V_{DS} = 15V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		50	_	рF	1 = 1.001112	
Gate Resistance	Rg		1.36	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg		4.5	_	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	9.9	_	nC	$V_{DS} = 15V, I_D = 5.8A$	
Gate-Source Charge	$Q_{gs}$		1.2	_	nC	$V_{DS} = 15V, I_{D} = 5.6A$	
Gate-Drain Charge	$Q_{gd}$	_	1.8	_	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.0	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	3.3	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	10.6	_	ns	$R_L = 2.6\Omega$ , $R_G = 3\Omega$	
Turn-Off Fall Time	t <sub>F</sub>		2.0	_	ns		
Reverse Recovery Time	t <sub>RR</sub>		7.9	_	ns	$I_F = 4.8A$ , di/dt = 100A/ $\mu$ s	
Reverse Recovery Charge	$Q_{RR}$	_	2.4	_	nC	$I_F = 4.8A$ , $di/dt = 100A/\mu s$	

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
  Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. IAS and EAS rating are based on low frequency and duty cycles to keep  $T_J = +25$ °C.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.



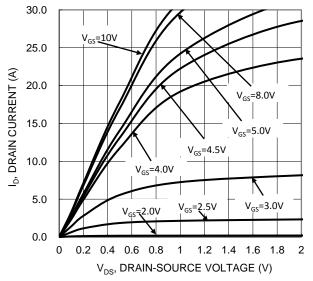
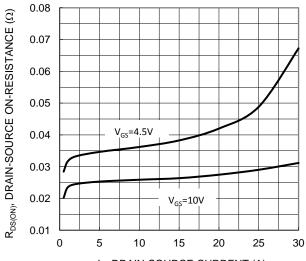


Figure 1 Typical Output Characteristic



I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

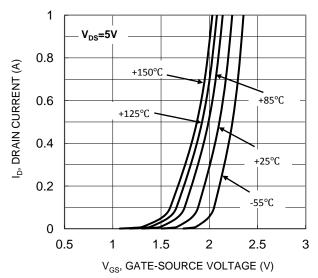


Figure 2 Typical Transfer Characteristic

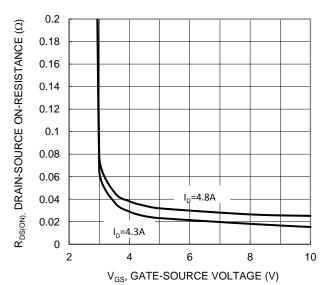


Figure 4 Typical Transfer Characteristic



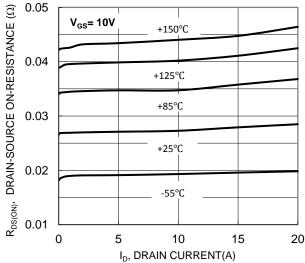


Figure 5 Typical On-Resistance vs Drain Current and Temperature

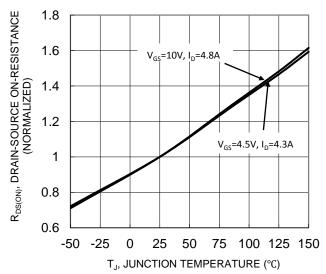


Figure 6 On-Resistance Variation with Temperature

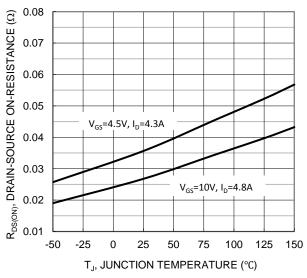
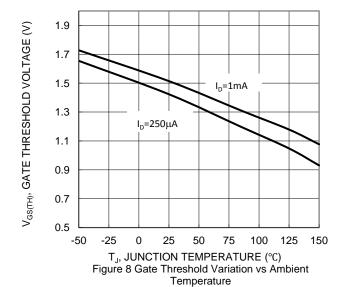


Figure 7 On-Resistance Variation with Temperature





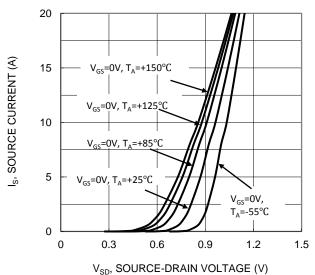
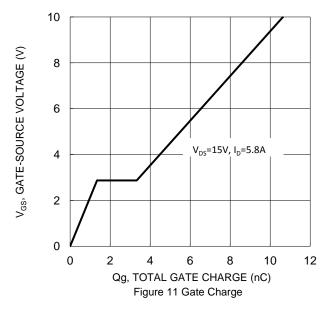


Figure 9 Diode Forward Voltage vs. Current



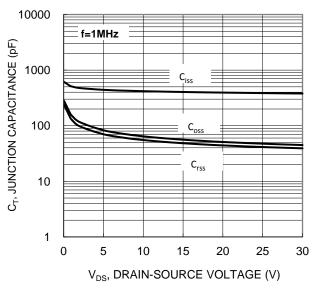
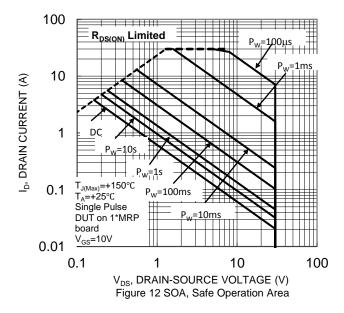


Figure 10 Typical Junction Capacitance





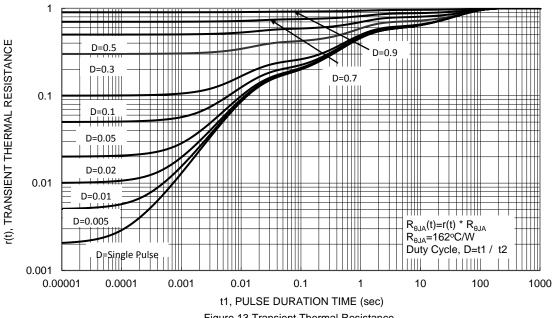
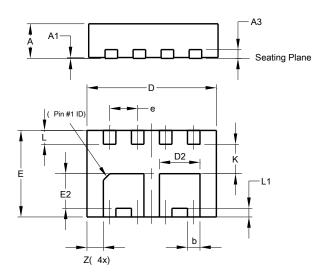


Figure 13 Transient Thermal Resistance

## **Package Outline Dimensions**

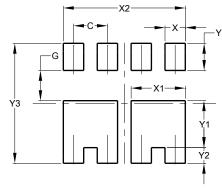
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



V-DFN3020-8										
	(Type N)									
Dim	Min	Max	Тур							
Α	0.77	0.83	0.80							
A1	0	0.05	0.02							
A3	1	1	0.203							
b	0.24	0.34	0.29							
D	2.95	3.05	3.00							
D2	0.84	1.04	0.94							
е	1	-	0.65							
Е	1.95	2.05	2.00							
E2	0.70	0.90	0.80							
٦	0.27	0.37	0.32							
L1	0.15	0.25	0.20							
K	1	1	0.68							
Z	-	-	0.38							
All	All Dimensions in mm									

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version



Dimensions	Value
Dilliensions	(in mm)
С	0.650
G	0.580
X	0.390
X1	1.040
X2	2.340
Y	0.520
Y1	0.900
Y2	0.300
Y3	2.300



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